

REMARKS

In the present amendment, claim 1 has been amended. Accordingly, claims 1-16 are pending in the application with claim 1 being independent.

Applicants note that claim 1 has been amended to even more clearly recite the claimed invention and to better comply with idiomatic English and standard U.S. practice. Support for the amendment can be found throughout the specification, and, e.g., Figures 1 and 2.

Response to Rejections under 35 U.S.C. § 112, second paragraph

The Office Action rejects claim 1 under 35 U.S.C. § 112, second paragraph, as allegedly being indefinite, because of the phrases “normal temperature” and “reaction temperature close to the melting point of the solder particle” need to be better specified. Furthermore, the Examiner states that there is insufficient antecedent basis for the phrase “the melting point.”

In response, Applicants submit that claim 1 has been amended to even further clarify the meaning of the claim and to better comply with idiomatic English standard U.S. practice. Accordingly, in view of the claim amendments, Applicants respectfully request withdrawal of the indefiniteness rejection.

Response to rejections under 35 U.S.C. § 102(b)

The Office Action rejects claims 1 and 3-16 under 35 U.S.C. § 102(b) as allegedly being anticipated by PCT/JP02/09946 to Saito et al., making specific references to its U.S. national stage application U.S. 2004/0259129, hereinafter “SAITO.”

Applicants respectfully traverse the rejection. Applicants submit that in an attempt to advance prosecution of the application and without expressing agreement with or acquiescence to the rejection, independent claim 1 has been amended to render the rejection moot.

Applicants note that present claim 1 recites: "A solder composition made of a mixture of a liquid substance and solder particles; wherein the liquid substance comprises a flux component which reacts at a melting point of the solder particles; the mixture of the liquid substance and solder particles has a viscosity that flows at room temperature and deposits in layers on a base material; and the solder particles are mixed in the liquid substance at room temperature, and are granular agents that precipitate in the liquid substance towards the base material, having a mixing ratio and a particle diameter to be uniformly dispersible within the liquid substance." Applicants note that SAITO requires the use of a solder paste which is applied "by printing the solder paste through a metal mask using a solder printer with an ordinary method," see SAITO, paragraph [0116]. In contrast, the present invention employs a mixture of a liquid substance and solder particles that flows at room temperature, which provides a uniform dispersion of the solder particles within the liquid and evenly spreads around a base material. In due course, the bump forming method of the presently claimed invention is fundamentally different from the method disclosed in SAITO.

For at least the foregoing reasons, SAITO fails to teach all elements of the presently claimed invention, wherefore withdrawal of the anticipation rejection is respectfully requested.

Response to rejections under 35 U.S.C. § 103(a)

The Office Action rejects claim 2 under 35 U.S.C. § 103(a) as allegedly being obvious over SAITO in view of U.S. Patent Application Publication 2003/0047034 to Ono et al., hereinafter ONO.

Applicants respectfully note that the obviousness rejection of claim 2 is based upon the assumption that claim 1 is anticipated by SAITO. Applicants submit that at least for the reasons discussed above, SAITO does not anticipate the presently claimed invention. Further, claim 2 merely specifies the mixing ratio of the solder particles in the mixture, and therefore, claim 2 is patentable for the same reason that claim 1 is patentable over SAITO. ONO does not cure or supply the deficiency of SAITO by merely teaching an additional aspect of claim 1.

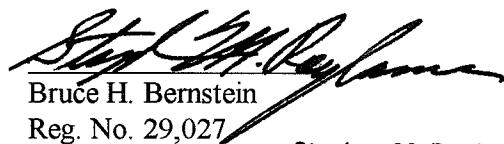
Accordingly, Applicants respectfully request withdrawal of the obviousness rejection of claim 2.

CONCLUSION

In view of the foregoing, the Examiner is respectfully requested to reconsider and withdraw the rejections of record, and allow each of the pending claims. Applicants therefore respectfully request that an early indication of allowance of the application be indicated by the mailing of the Notices of Allowance and Allowability.

Should the Examiner have any questions regarding this application, the Examiner is invited to contact the undersigned at the below-listed telephone number.

Respectfully submitted,
Isao SAKAMOTO et al.



Bruce H. Bernstein
Reg. No. 29,027

Stephen M. Roylance
Reg. No. 31,296

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GREENBLUM & BERNSTEIN, P.L.C.
1950 Roland Clarke Place
Reston, Virginia 20191
(703)716-119